



Material Content Data Sheet



Sales Product Name		CDM10V-2		Issued		20. July 2018			
MA#		MA001687172							
Package		PG-SOT23-6-1		Weight*		18.49 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.215	1.16	1.16	11610	11610	
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		118		
	non noble metal	zinc	7440-66-6	0.009	0.05		473		
	non noble metal	iron	7439-89-6	0.175	0.95		9455		
wire	non noble metal	copper	7440-50-8	7.097	38.39	39.40	383905	393951	
	noble metal	gold	7440-57-5	0.059	0.32	0.32	3214	3214	
	encapsulation	organic material	carbon black	1333-86-4	0.020	0.11		1093	
encapsulation	plastics	epoxy resin	-	1.546	8.36		83649		
	inorganic material	silicondioxide	60676-86-0	8.540	46.21	54.68	461983	546725	
leadfinish	non noble metal	tin	7440-31-5	0.465	2.51	2.51	25144	25144	
plating	noble metal	silver	7440-22-4	0.167	0.90	0.90	9038	9038	
glue	plastics	acrylic resin	-	0.042	0.23		2270		
	noble metal	silver	7440-22-4	0.149	0.80	1.03	8048	10318	
*deviation	< 10%				Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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